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SANYO Semiconductors DATA SHEET

N-Channel Silicon MOSFET

General-Purpose Switching Device Applications

Features

- · Low ON-resistance.
- 2.5V drive.
- Mount height 1.1mm.
- Composite type, facilitating high-density mounting.
- Drain common specifications.

FTD2017R

Specifications

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Conditions	Ratings	Unit			
Drain-to-Source Voltage	VDSS		20	V			
Gate-to-Source Voltage	VGSS		±12	V			
Drain Current (DC)	ID	- COM	6	А			
Drain Current (Pulse)	IDP	PW≤10µs, duty cycle≤1%	40	А			
Allowable Power Dissipation	PD	Mounted on a ceramic board (1000mm ² ×0.8mm)1unit	1.2	W			
Total Dissipation	PT	Mounted on a ceramic board (1000mm ² ×0.8mm)	1.25	W			
Channel Temperature	Tch		150	°C			
Storage Temperature	Tstg		-55 to +150	°C			

Electrical Characteristics at Ta=25°C

Parameter	Symbol	Conditions	Ratings			1.1
			min	typ	max	Unit
Drain-to-Source Breakdown Voltage	V(BR)DSS	ID=1mA, VGS=0V	20			V
Zero-Gate Voltage Drain Current	IDSS	VDS=20V, VGS=0V			1	μΑ
Gate-to-Source Leakage Current	IGSS	V _{GS} = ±8V, V _{DS} =0V			±10	μΑ
Cutoff Voltage	V _{GS} (off)	V _{DS} =10V, I _D =1mA	0.5		1.3	V
Forward Transfer Admittance	yfs	VDS=10V, ID=6A	6.9	11.5		S
Static Drain-to-Source On-State Resistance	R _{DS} (on)1	ID=6A, VGS=4.5V	11	17	23	mΩ
	R _{DS} (on)2	ID=6A, VGS=4V	12	18	24	mΩ
	RDS(on)3	ID=3A, VGS=3.1V	14	19	30	mΩ
	R _{DS} (on)4	ID=3A, VGS=2.5V	14.4	20	33	mΩ

Marking : D2017R

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SANYO Semiconductor Co., Ltd.

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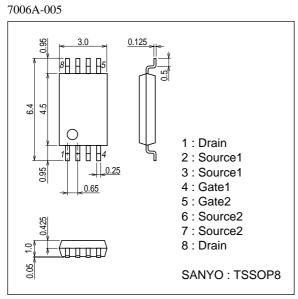
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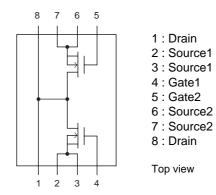
Parameter	Symbol	Conditions		Ratings		
	Symbol		min	typ	max	Unit
Turn-ON Delay Time	t _d (on)	See specified Test Circuit.		960		ns
Rise Time	tr	See specified Test Circuit.		2700		ns
Turn-OFF Delay Time	t _d (off)	See specified Test Circuit.		5500		ns
Fall Time	tf	See specified Test Circuit.		5400		ns
Total Gate Charge	Qg	V _{DS} =10V, V _{GS} =4.5V, I _D =6A		10		nC
Gate-to-Source Charge	Qgs	V _{DS} =10V, V _{GS} =4.5V, I _D =6A		1		nC
Gate-to-Drain "Miller" Charge	Qgd	V _{DS} =10V, V _{GS} =4.5V, I _D =6A		4		nC
Diode Forward Voltage	V _{SD}	IS=6A, VGS=0V		0.83	1.2	V

Package Dimensions

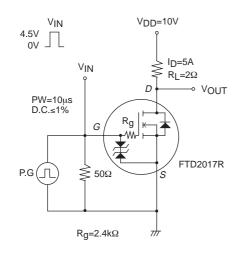
unit : mm (typ)



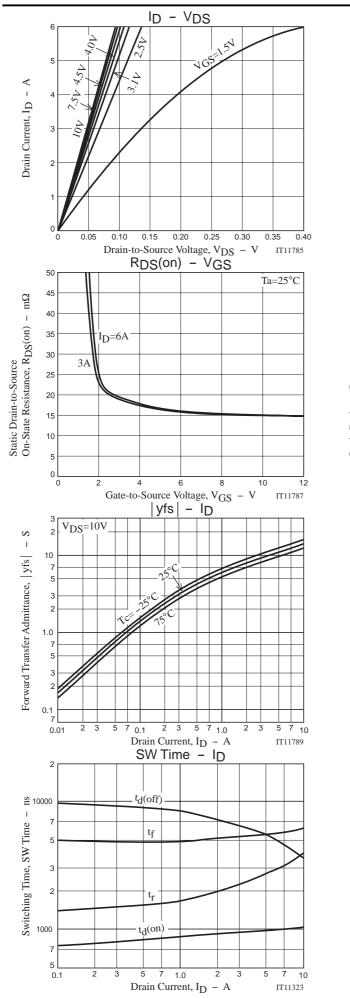
Electrical Connection

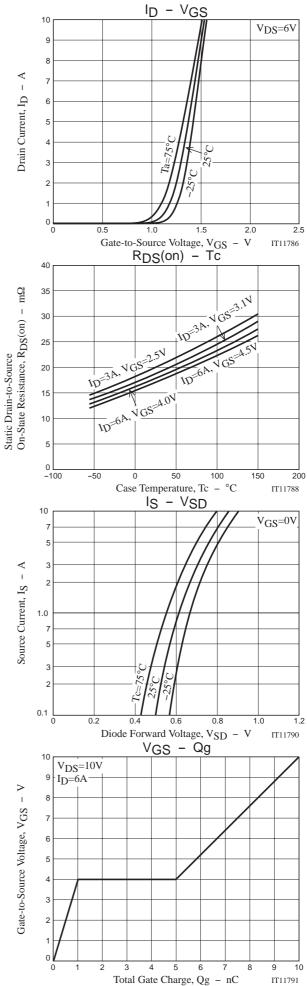


Switching Time Test Circuit

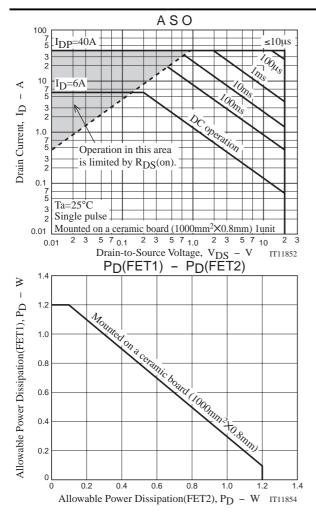


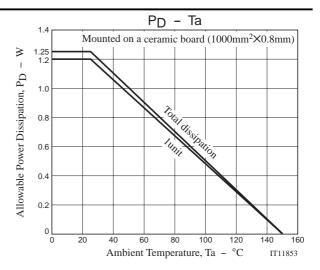
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Note on usage : Since the FTD2017R is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

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